

Microfabrication Lab 2009 Summer Internship

UC Berkeley-EECS



Characterizing Aluminum uniformity using resistance



By: Anjana Bala
Mission San Jose
High School

Outline



- First week
 - Clean Room Procedure
- My Project
 - Objective
 - Define Terms
- Procedure
- Results (4 inch wafers)
- Results (6 inch wafers)
- Graphs and Analysis
 - Conclusion
- Acknowledgments



Clean Room Procedure



- First thing I learned was importance of minimizing contamination
- Always suit up: Hair cap, bunny suit, blue booties, white booties, goggles, gloves
- From human saliva to a small piece of junk, anything can mess up a wafer



My Project



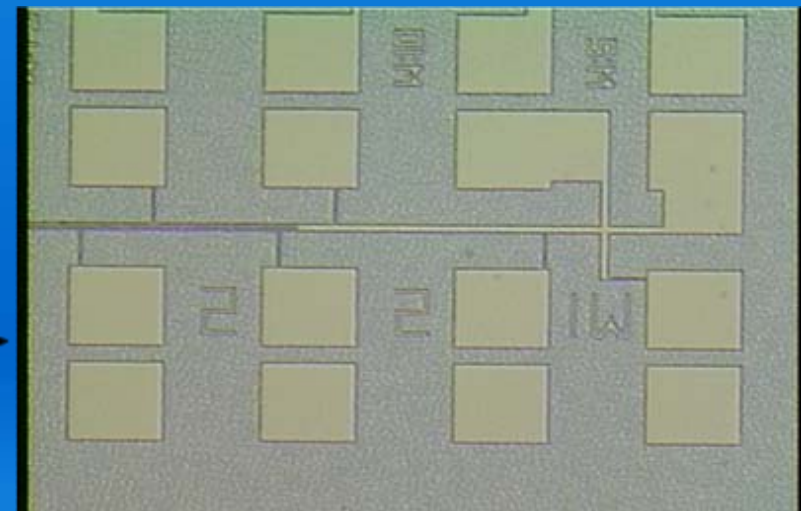
Objective: To measure Aluminum uniformity with NRC and V401 using resistance: 4" to 6" wafer upgrade

Terms:

- Resistance:
 - A measure of how strongly a material opposes the flow of electric current.
 - Measured in Ohms (Ω)
 - A low resistance = thicker film
 - A high resistance = thinner film

$$R = \rho \frac{L}{wt}$$

Split Cross Bridge \longrightarrow

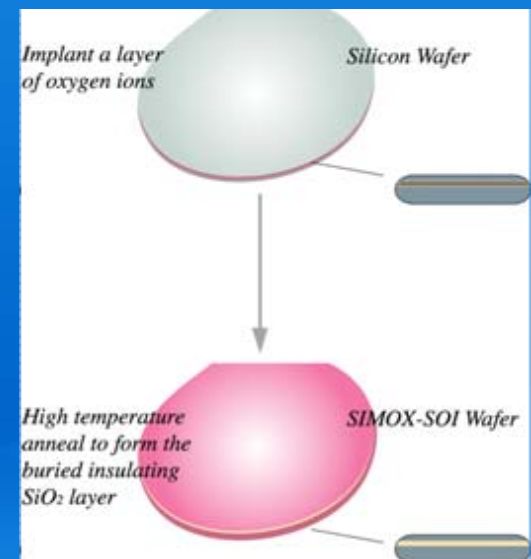


Procedure



Step One: Grow Oxide Layer

- Pirana bath ($\text{H}_2\text{SO}_4 + \text{H}_2\text{O}_2$)
- DI water rinse (4 cycles)
- Spin dryers
- Run Recipes--> Tystar furnace
- Silicon is very conductive; oxide layer serves as an insulator

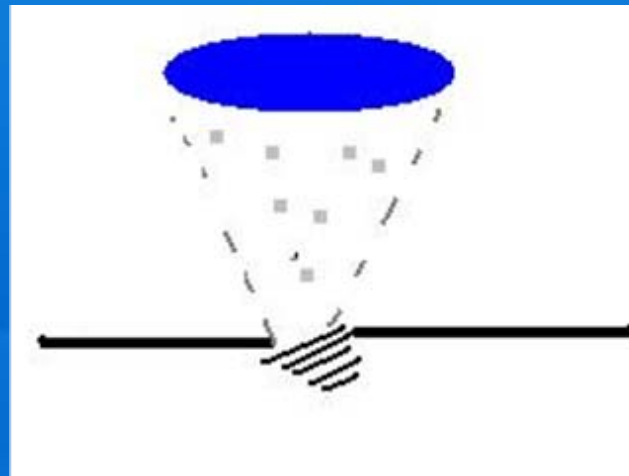


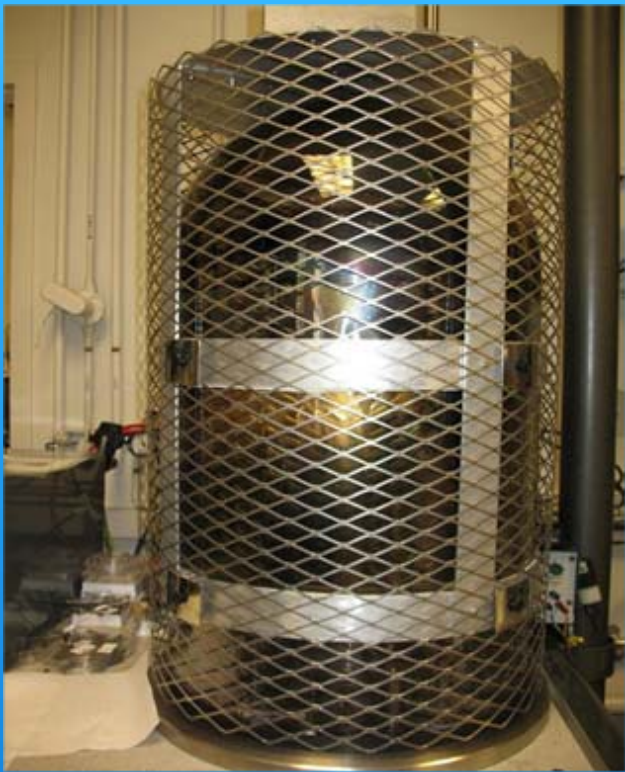
Procedure



Step Two: Evaporate Aluminum onto Wafer

- Two thermal evaporation systems: NRC and V401
- Pumps out gas and pumps down the chamber
- Ran current through the filament
- Metal heats up and becomes a gas
- Condenses back to solid when metal reaches the wafer





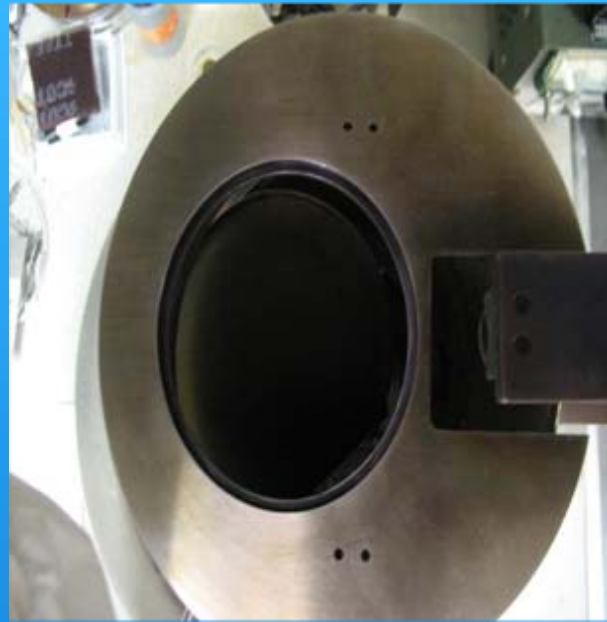
NRC



V401



Closed Shutter



Deposition Conditions



V401

NRC

Pressure:

- 4×10^{-6}

- 4×10^{-6}

Current:

wire basket
flat boat

- 38 amps
- 250 amps

- 39 amps
- 247 amps

Deposition

Rate:

- 5-7 Å/Sec

- 5-7 Å/Sec

Time:

- 3 minutes

- 3 minutes



Procedure

Step Three: Put a layer of BARC (6" only)

- BARC stands for Bottom Anti-Reflective Coating
- Aluminum is extremely reflective
- Minimizes reflections from Aluminum that could degrade the patterning
- Used svgcoat6
- Followed by a softbake

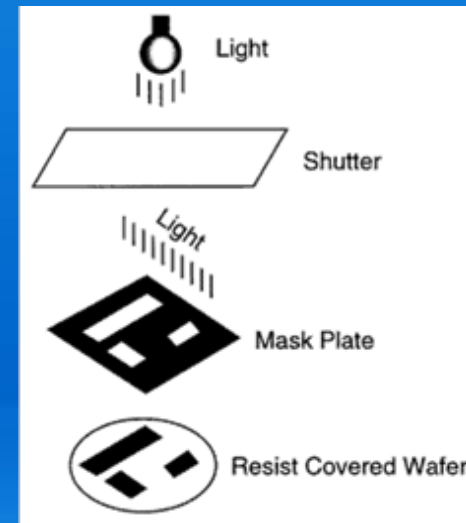


Procedure



Step Four and Five: Add Photoresist and Photo lithography

- I-Line Photoresist
- Shine light through to form a pattern (Quintel for 4" and gcaws6 for 6")
- Light transfers a geometric pattern to the photoresist
- Developed on svgdev6 (6") and manually (4")
- Finished with UV Bake to make photoresist hard and durable for etching



Procedure



Step Six and Seven: Metal Etch and Removing Photoresist

- Wet Etch for 4" (Patterns on 4" were larger)
- Centura for 6"
- Centura removed Photoresist in 6" wafers whereas 4" were put into matrix
- Ready for testing
 - 2 point probe, Autoprobe, and ASIQ to measure 4" wafer resistance, 6" wafer sheet resistance, and 4" wafer Aluminum thickness.



Results 4"

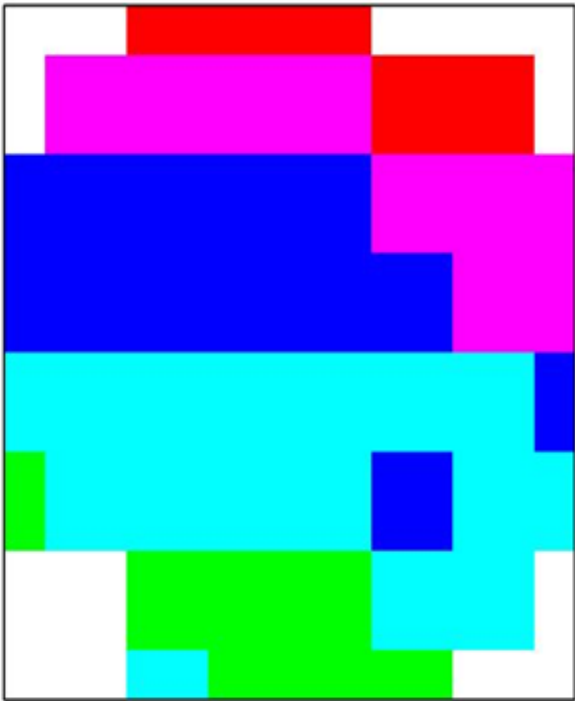


V401

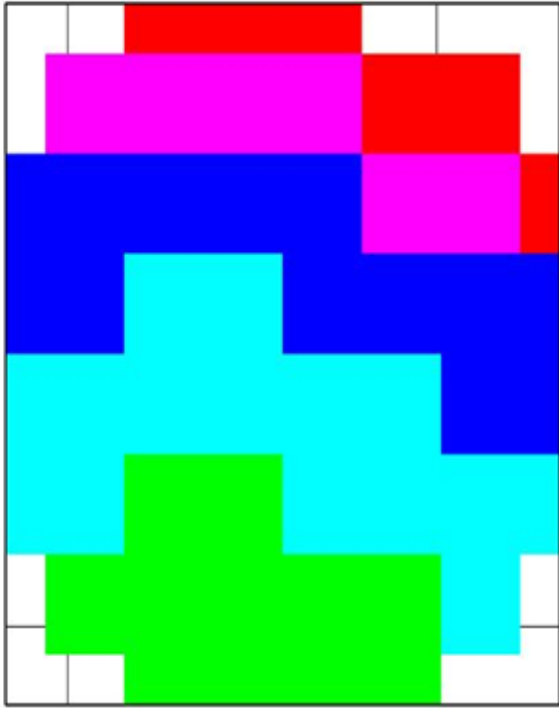
NRC

Higher Resistance

Wafer A2: v401



Wafer A1: nrc



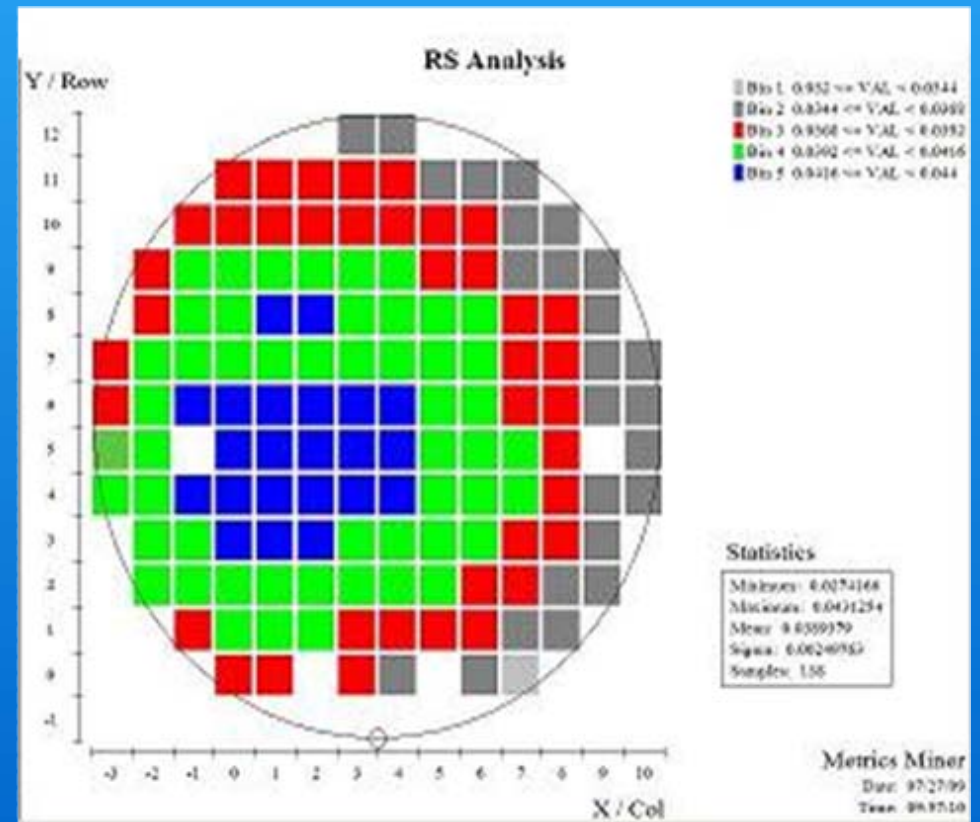
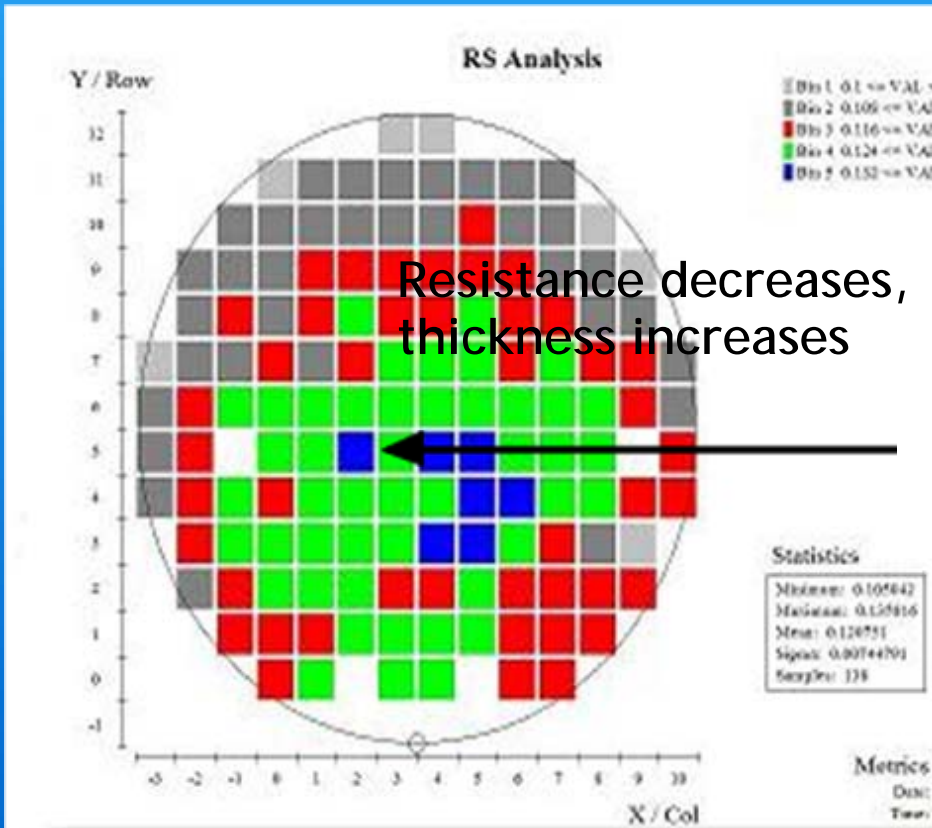
Thicker Film

Results 6"



V401

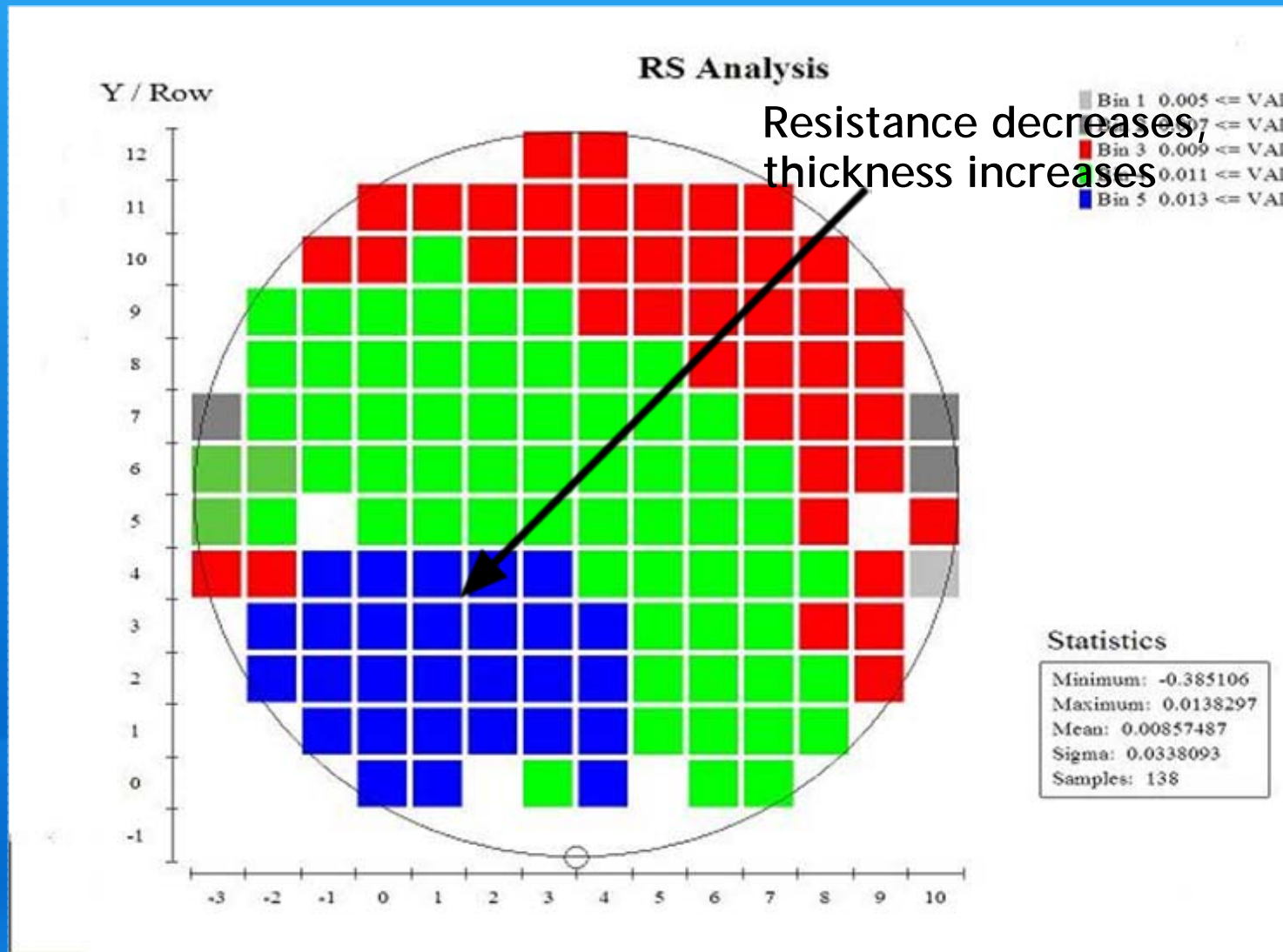
NRC





Results

6" with shutter closed and then opened



Data Analysis



Non uniformity: $100 \times \frac{\text{Max-Min}}{\text{Average}}$

	4"	6"
NRC	Wafer A1 25.5%	Wafer 16 40.3%
V401	Wafer A2 31.0%	Wafer 18 25.4%
		Wafer 24 100.16% (closed shutter)

Conclusion



- In both the 4" and 6" wafers, the percentage of non-uniformity equally poor
- Indicated that the uniformity is not considerably worse when upgraded to 6 "
- 4" Sloping Gradient vs 6" Bands
- When the shutter is closed, and then opened, thickness gradient is very uneven ; shutter should be replaced.
- If the chimney is taller, the uniformity will be better because it will have a larger diameter (although thinner)
- Or move the source lower
- Either way will increase the distance, which increases uniformity

Acknowledgments



Thank you to everyone who made the Microlab a friendly environment and made this experience very enjoyable.

Madeleine Leullier
Ryan

Sia Parsa
Rosemary Spivey

Marilyn Kushner
Adrienne Ruff

Jimmy Chang
Kim Chan
Lazlo Petho





Special Thanks:

Thank you to Katalin Voros for this AMAZING opportunity.

Daniel Queen for being the best mentor I could have ever asked for. Your patience, understanding, and thoughtfulness made this project a true success.



THE END

